

**Amendments to the Claims**

Claim 1-53 (cancelled).

Claim 54 (previously presented): A method for removing organic materials comprising removing at least a portion of an organic-material-comprising layer from a semiconductive substrate surface with a pad and a fluid, the fluid being substantially unreactive with the surface and comprising less than or equal to about 0.1 weight percent particles at an initiation of the removing.

Claim 55 (previously presented): The method of claim 54 wherein the organic-material-comprising layer comprises one or more of photoresist, non-photosensitive resist, and polyimide.

Claim 56 (previously presented): The method of claim 54 wherein a pH of the fluid is from about 8 to about 12.

Claim 57 (previously presented): The method of claim 54 wherein the fluid comprises one or both of ammonia and TMAH.

Claim 58 (previously presented): The method of claim 54 wherein the fluid comprises water.

Claim 59 (previously presented): The method of claim 54 wherein the surface comprises a conductive material.

Claim 60 (withdrawn): The method of claim 59 wherein the conductive material comprises one or more of platinum, iridium, ruthenium, and tantalum.

Claim 61 (previously presented): The method of claim 54 wherein the surface comprises a barrier material.

Claim 62 (withdrawn): The method of claim 61 wherein the barrier material comprises one or both of tantalum silicon nitride and tantalum nitride.

Claim 63 (previously presented): The method of claim 54 wherein the pad comprises polyurethane.

Claim 64 (previously presented): The method of claim 54 wherein at least some of the particles comprise silica.

Claim 65 (previously presented): The method of claim 54 wherein the surface comprises at least two layers, a first conductive layer of the two layers comprising N and Si, and a second conductive layer of the two layers comprising N.

Claim 66-73 (cancelled).